

APPARATUS AND METHOD FOR SOLDER FLUX TRANSFER

ABSTRACT OF THE DISCLOSURE

5 An apparatus for the transfer of solder flux from
a solder flux plate onto a printed circuit substrate in a
solder ball mounting process comprising a plurality of
solder flux transfer pins, a housing for supporting the
transfer pins, and an air cylinder for supplying air
10 pressure into the housing thereby generating a
predetermined minimum force to hold down the transfer pins
and to allow the transfer pins to yield and retract into
the housing when the transfer pins are in contact with the
circuit substrate during the transfer of solder flux from
15 the solder flux transfer pins onto the circuit substrate.
A method for the transfer of solder flux is also disclosed.

Fig. 3